

Layer Material	Layer (File) Name	Thickness (mm)	Permittivity	Loss Tangent
Silkscreen	F.Silk	0.00762	-----	-----
Soldermask	F.Mask	0.0254	4.5	0.029
Copper	F.Cu	0.0432	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	In1.Cu	0.0175	-----	-----
FR408-HR	-----	0.9906	3.64	0.0098
Copper	In2.Cu	0.0175	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	B.Cu	0.0432	-----	-----
Soldermask	B.Mask	0.0254	4.5	0.029
Silkscreen	B.Silk	0.00762	-----	-----

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5670 mm
Board overall dimensions:	52.5000 mm x 40.5000 mm	Min hole diameter:	0.3000 mm
Min track/spacing:	0.415 mm / 0.300 mm	Impedance Control:	Yes
Copper Finish:	ENIG	Plated Board Edge:	No
Castellated pads:	No		
Edge card connectors:	No		

Notes:
LNA footprint is pin-compatible with PMA2-123LN+.

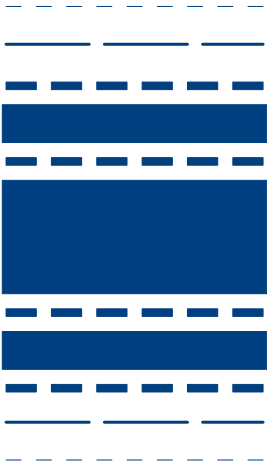
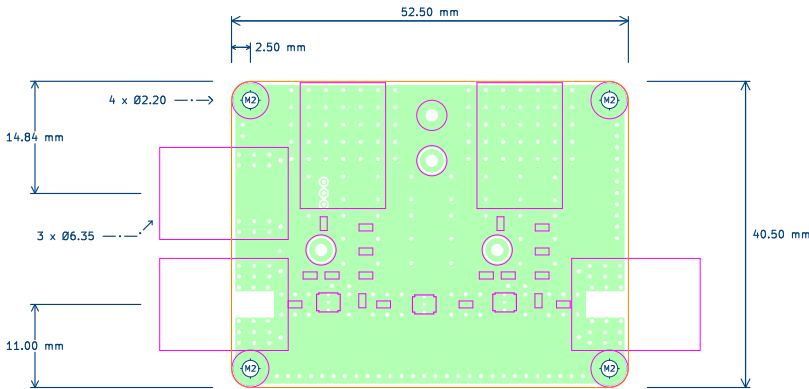
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Sheet:
File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit

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Rev: c
Id: 1/1



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Copper	B.Cu	0.0432	-----	-----
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Silkscreen	B.Silk	0.00762	-----	-----

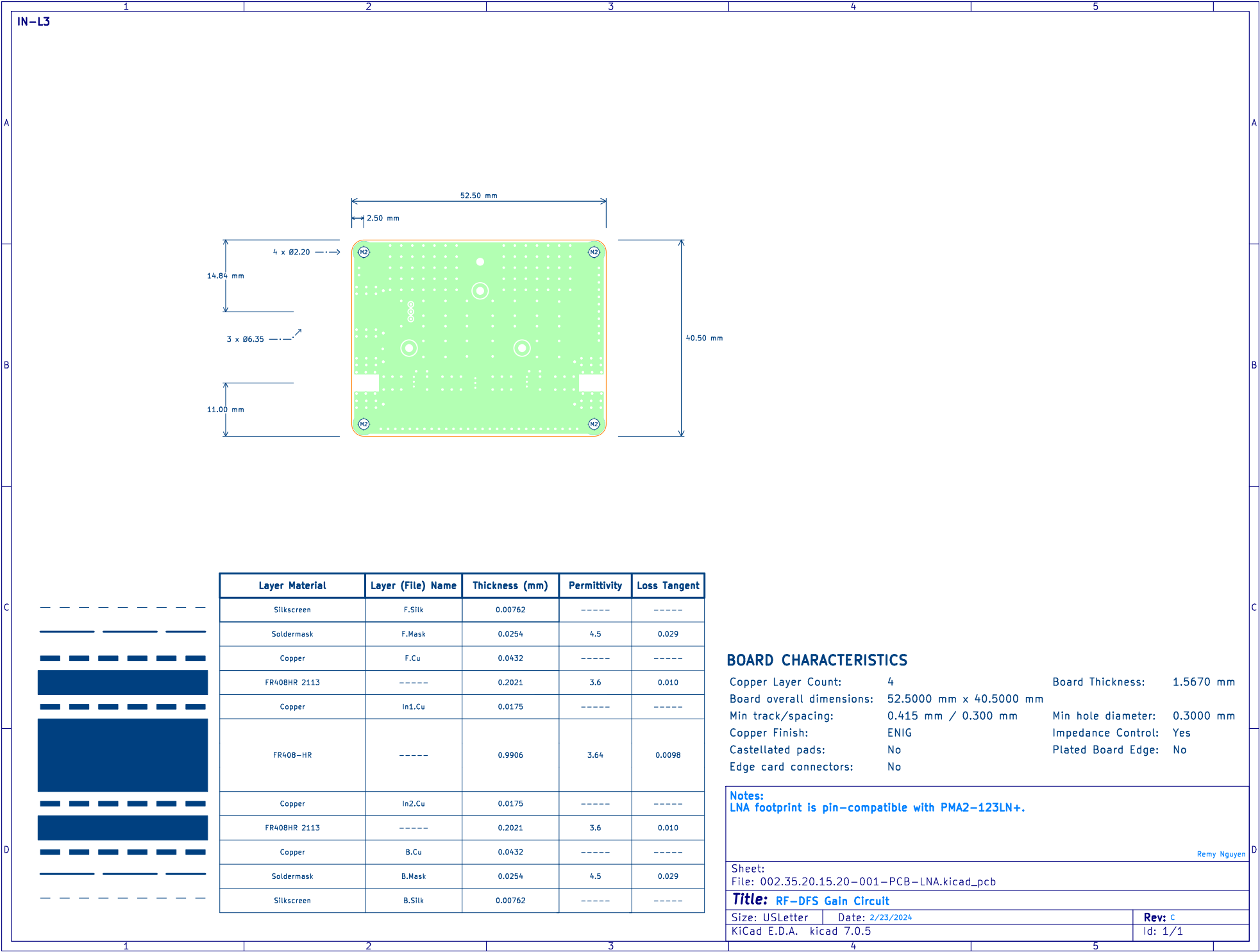
BOARD CHARACTERISTICS

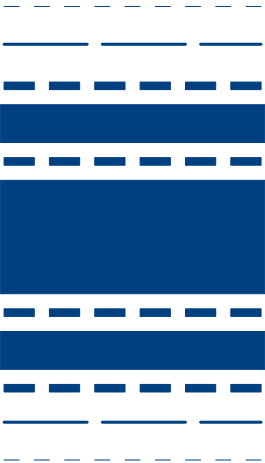
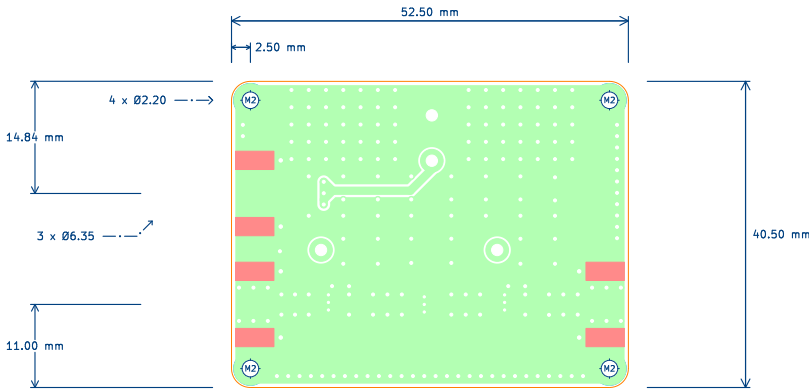
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